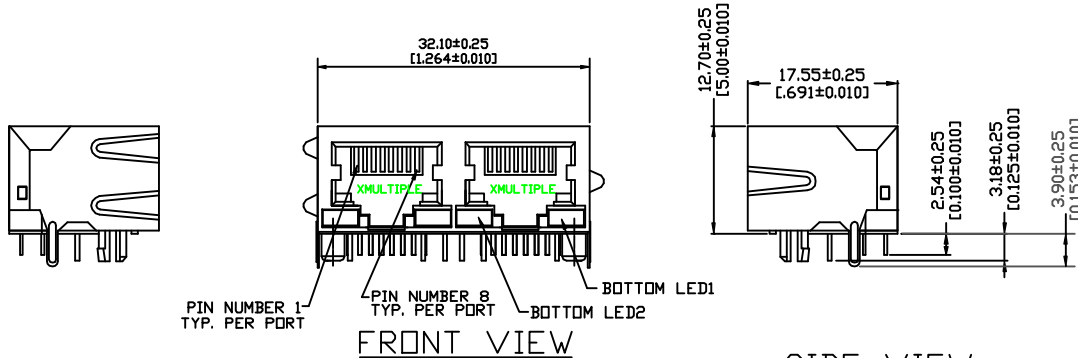
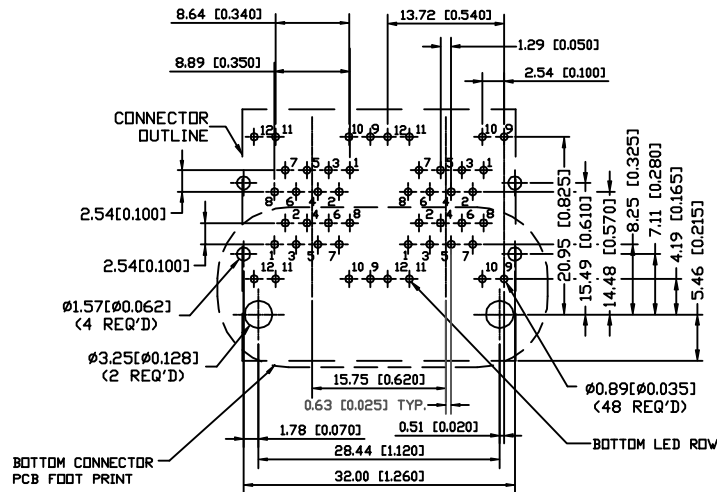


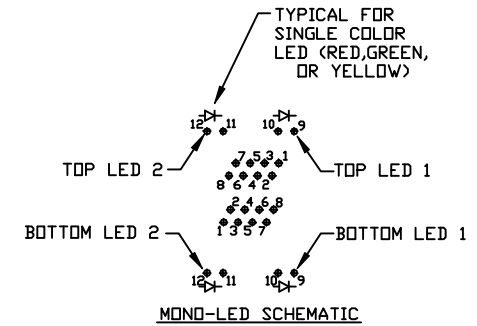
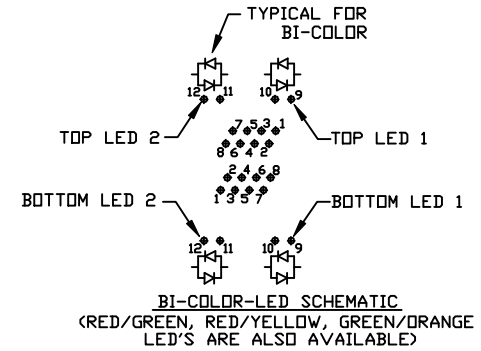
REVISIONS					
ECO	ZONE	REV	DESCRIPTION	DATE	APPROVED
		A	INITIAL RELEASE	06/09/05	Chen



SIDE VIEW



SUGGESTED PCB LAYOUT (COMPONENT SIDE)



1. MATERIALS:
 HOUSING: HIGH TEMP. THERMOPLASTIC, BLACK, UL 94V-0
 CONTACTS: 0.014 INCHES (0.35 MILLIMETERS) THICK PHOSPHOR BRONZE PLATED WITH 150 MICROINCHES (3.81 MICROMETERS) MINIMUM THICK TIN LEAD IN SOLDER AREA.
 15 MICROINCHES (0.38 MICROMETERS) MINIMUM GOLD IN LOCALIZED PLATE AREA.
 ENTIRE CONTACTS PLATED WITH 50 MICROINCHES (1.27 MICROMETERS) MINIMUM THICK NICKEL.
 SHIELDED: 0.0098 INCHES (0.25 MILLIMETERS) THICK COPPER ZINC ALLOY PLATED WITH 30 MICROINCHES (0.762 MICROMETERS) MINIMUM THICK NICKEL.

2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F

3. PART NUMBER: XRJD-S-22-8-B-X
 REFER TO LED OPTIONS TABLE FOR ORDERING CODES

NOTES: UNLESS OTHERWISE SPECIFIED
 UNSPECIFIED TOLERANCE: .XX±0.010(0.25)
 .X±0.006(0.15)

XMULTIPLE		CONNECTING THE INFORMATION AGE	
XMULTIPLE ASIA 11P-1, No. 70, Pi-Hsing N. Road Taipei, Taiwan, R.O.C.		XMULTIPLE USA 8996 Old County Road Hayward, CA 94588	
THIS DRAWING IS A CONTROLLED DOCUMENT.			
TITLE: Stacked RJ45 Connectors, V/CD, 8P, 8C, Shielded, Thru Hole, Bottom Piece			
PART NO: XRJD-S-02-8-B-X		REV: A	
DIMENSIONS: [mm]/inch		SHEET: 1 of 1	
DRAWN: VIQ		DATE: 07/31/01	
CHKD: C. TSAI		REV: A	